



# Initial Product/Process Change Notification

Document #: IPCN21520XF

Issue Date: 30 Sep 2022

<b>Title of Change:</b>	Qualification of onsemi Aizu as an additional Wafer Fab facility for ONC25 Technology - NCP711 & NCP730 family.
<b>Proposed First Ship date:</b>	01 Sep 2023 or earlier if approved by customer
<b>Contact Information:</b>	Contact your local onsemi Sales Office or <a href="mailto:Jan.Gryzbon@onsemi.com">Jan.Gryzbon@onsemi.com</a>
<b>PCN Samples Contact:</b>	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
<b>Type of Notification:</b>	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a> >
<b>Marking of Parts/ Traceability of Change:</b>	The affected products will be identified with date code and custom source
<b>Change Category:</b>	Wafer Fab Change
<b>Change Sub-Category(s):</b>	Manufacturing Site Addition

**Sites Affected:**

onsemi Sites	External Foundry/Subcon Sites
onsemi Aizu, Japan	None

**Description and Purpose:**

This Product Change Notification is to announce that onsemi Aizu Wafer Fab located in Aizuwakamatsu, Japan has been qualified to process the ONC25 CMOS process.

The exact same process technology has been transferred as is currently running in the onsemi wafer fab located at Gresham, Oregon, USA.

Tool sets are different but the exact same masking layers and steps are being used in the onsemi Aizu.

This is a capacity expansion to supplement the existing onsemi wafer fab.

The parts being qualified are dual sourced and may be processed at either wafer fab in the future depending on capacity requirements.

Additional part families will be announced on future PCNs once qualifications of those parts are completed.

This PCN will apply to future Regulator output voltage versions of the part families listed below.

There is no change to the orderable part number. There is no product marking change as a result of this change.

Site / Location	Current:	Proposed:
<b>Wafer Fab:</b>	onsemi Gresham, North America United States Oregon	onsemi Aizu, Asia Japan Fukushima onsemi Gresham, North America United States Oregon



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## Qualification Plan:

**QV DEVICE NAME:** NCP730ASNxxxT1G

**PACKAGE:** TSOP5

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
ELFR	JESD22-A108	Ta= 125°C	48 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C, 3x IR reflow	
TC	JESD22-A104	Ta= -55°C to +150°C	500 cyc
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
HBM	JS001	2kV	
CDM	JS002	1kV	
LU	AEC-Q100-004, JESD78	Class II	
ED	ON Data Sheet		

Estimated date for qualification completion: **31 May 2023**

## List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
NCP730ASN330T1G	NCP730ASN330T1G
NCP730BMT330TBG	NCP730ASN330T1G
NCP711BMTADJTBG	NCP730ASN330T1G
NCP730ASNADJT1G	NCP730ASN330T1G
NCP730ASN500T1G	NCP730ASN330T1G
NCP730BMTADJTBG	NCP730ASN330T1G
NCP711ASN330T1G	NCP730ASN330T1G
NCP711BMT330TBG	NCP730ASN330T1G
NCP730BMT500TBG	NCP730ASN330T1G
NCP711ASN500T1G	NCP730ASN330T1G
NCP730ASN280T1G	NCP730ASN330T1G
NCP730BMT300TBG	NCP730ASN330T1G
NCP730ASN300T1G	NCP730ASN330T1G
NCP730ASN250T1G	NCP730ASN330T1G
NCP711ASNADJT1G	NCP730ASN330T1G
NCP711ASN300T1G	NCP730ASN330T1G
NCP730BMT250TBG	NCP730ASN330T1G



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NCP711BMT500TBG	NCP730ASN330T1G
NCP730BMT1500TBG	NCP730ASN330T1G
NCP730BMT280TBG	NCP730ASN330T1G
NCP711BMT300TBG	NCP730ASN330T1G

**Appendix A: Changed Products**

**PCN#: IPCN21520XF**  
**Issue Date: Sep 30, 2022**

DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NCP730ASN330T1G		NCP730ASN330T1G		
NCP711BMTADJTBG		NCP730ASN330T1G		
NCP730ASNADJT1G		NCP730ASN330T1G		
NCP730ASN500T1G		NCP730ASN330T1G		
NCP730BMTADJTBG		NCP730ASN330T1G		
NCP711ASN330T1G		NCP730ASN330T1G		
NCP711BMT330TBG		NCP730ASN330T1G		
NCP730BMT500TBG		NCP730ASN330T1G		
NCP711ASN500T1G		NCP730ASN330T1G		
NCP730BMT300TBG		NCP730ASN330T1G		
NCP711ASNADJT1G		NCP730ASN330T1G		
NCP711ASN300T1G		NCP730ASN330T1G		
NCP711BMT500TBG		NCP730ASN330T1G		
NCP711BMT300TBG		NCP730ASN330T1G		
NCP730BMT330TBG		NCP730ASN330T1G		